

METHOD FOR WAFER DICING AND COMPOSITION USEFUL THEREOF

ABSTRACT OF THE DISCLOSURE

A solution for semiconductor wafer dicing is disclosed. The solution suppresses
5 the adherence of contamination residues or particles, and reduces or eliminates the
corrosion of the exposed metallization areas, during the process of dicing a wafer by
sawing. The solution comprises at least one organic acid and/or salt thereof; at least a
surfactant and/or at least a base; and deionized water, the composition has a pH is equal
or greater than 4. The solution can further comprise, a chelating agent, a defoaming
10 agent, or a dispersing agent.

Fig. 1